PCN Number:	20221219004.1	PCN Date:	December 22, 2022
Title:	Qualification of CDAT as an alternate Assembly site for select devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Mar 22, 2023	Sample Requests accepted until:	Jan 22, 2023*

***Sample requests received after Jan 22, 2023 will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for set of devices listed below. Construction differences are as follows:

What	UTAC	CDAT
Mold Compound	SID#CZ0138	4222198
Mount Compound	SID#PZ0039	4226215 or 4221460 + 4226215
Bond wire composition, diameter	Au, 1.0 mil	Cu, 0.8 mil

Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
UTL1	NSE	THA	Bangkok
UTL3	Bangpakong	THA	Bangpakong
CDAT	**CDA**	**CHN**	**Chengdu**

Sample product shipping label (not actual product label)

Product Affected:

ADS1013IRUGR	ADS1113IRUGR	ADS1118IRUGT	TLA2024IRUGT
ADS1013IRUGT	ADS1113IRUGT	SN1507032RUGR	TLA4021IRUGR
ADS1014IRUGR	ADS1114IRUGR	TLA2021IRUGR	TLA4021IRUGT
ADS1014IRUGT	ADS1114IRUGT	TLA2021IRUGT	TLA4022IRUGR
ADS1015IRUGR	ADS1115IRUGR	TLA2022IRUGR	TLA4022IRUGT
ADS1015IRUGT	ADS1115IRUGT	TLA2022IRUGT	TLA4024IRUGR
ADS1018IRUGR	ADS1118IRUGR	TLA2024IRUGR	TLA4024IRUGT
ADS1018IRUGT			

TI Information
Selective Disclosure

Qualification Report

CDAT_Leadframe-LLGA-EOL_UTAC
Approve Date 05-December-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: ADS1115IRUGR	Qual Device: TLA4024IRUGR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-
MQ	-	Assembly MQ	-	-	3/3/0	3/3/0

- QBS: Qual By Similarity
- Qual Device ADS1115IRUGR is qualified at MSL1 260C
- Qual Device TLA4024IRUGR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2108-040

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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